

Standard Cell Library Characterization of 28nm Process Based on Machine Learning

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Abstract. This article presents a new learning method based on machine learning, which can quickly and accurately draw up the characterization of the Static Random-Access Memory (SRAM) compiler and standard cell library. The timing of 10 standard circuits with different process corners and their key parameters were collected. According to the 10-fold cross validation, the regression model was established by linear regression. After comparing the influence of different parameters on path delay, determination coefficient of training set and testing set were 0.979 and 0.955, respectively. Relative Error of training set and test set were 0.9458 and 0.8736, respectively. Then, the timing of a D type flip-flop (DFF) was selected as the target of the regression. At the same time, the determination coefficients of the regression model training set and the testing set are 0.9992 and 0.9992, respectively. Relative Error of training set and test set were 0.9882 and 0.9868, respectively. The results show that the model fitted the timing of DFF by the path delay of other circuits is better than the previous method.

Introduction

Since Dynamic Voltage and Frequency Scaling (DVFS) was introduced into System on Chip (SOC), SOC worked under hundreds of megabytes clock frequency. Similarly, SRAM, as an important part of SOC, needed to work under the same clock frequency [1]. A SRAM compiler has thousands of instances, for one instance, it's simulation in different process variations must be implemented to achieve characterization.

DVFS makes the SOC design voltage nodes for signoff increase a lot. In the case of 28nm low power, standard working voltage is 1.1v, which corresponds to 6 corners need signoff. The median voltage range is from 0.7v to 1.2v, taking each 50mv as a node, a total of 66 corners requires signoff [2]. Namely, it means that there must be 66 corners of memory and standard cell library characterization.

With 30 servers and enough EDA tool licenses, characterization of one memory compiler may need 2 weeks. Based on machine resources and time cost, the characterization data of compiler are typical values. The purpose of this project is to use machine learning to write efficient algorithms and programs, and to predict other characteristics of the unknown instance by using the known characterization of instance.

Standard Cell Library Simulation

In semiconductor design, standard cell methodology is a method of designing application specific integrated circuits (ASICs) with mostly digital-logic features. Considered that time cost of SRAM compiler, we used standard cell library of 28nm process to make a test, and 10 circuits of standard cell library are INV, AND2, AND3, NOR2B, NOR2, AOI211, XOR3, ADDF, DFFNQ, DFFNSRPQ.

Table 1. 325 Sets of process corners.

Process	FNFP	SNSP	TNTP	FNFP	SNFP								
Voltage [V]	0.84	0.875	0.91	0.945	0.98	1.015	1.05	1.085	1.12	1.155	1.19	1.225	1.26
Temperature [°C]	-40	0	25	85	125								

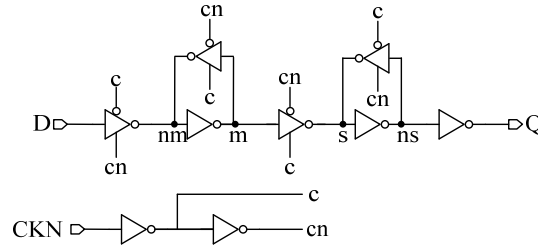


Figure 1. DFF functional schematic.

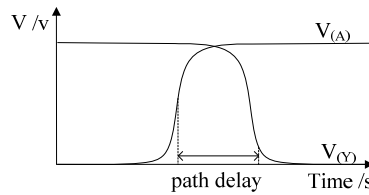


Figure 2. Path delay: from input 50% transition to output low 10% transition.

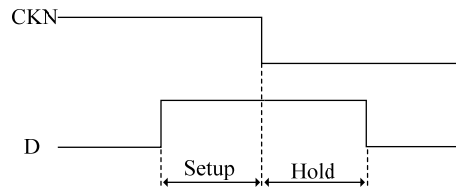


Figure 3. Setup time and fold time of DFF.

Due to process deviation, even on the same wafer chip, the device properties may be different in different locations. Take MOS transistor as an example, although they have similar resistors and capacitors, there will be different states, such as FNFP, SNSP, TNTP, FNFP, SNFP, which show difference of threshold voltage and some other parameters. Exclude process deviation, the performance of MOS transistor is also affected by voltage and temperature, Generally, we choose -40, 0, 25, 85, 125 as the temperature node, and $\pm 20\%$ of standard voltage as voltage range. To meet with a sufficient number of sample data, we adjusted the voltage value of the number. There are 325 sets of process corners in Table 1, which are composed of process, voltage and temperature.

All simulation used H-Spice which based on Bsim4 spice model, and slew is set to 1ns. Path delay is the time from the input pin to the output pin. Take DFFs as an example, as shown in Fig. 1 and Fig. 2, pin D is input terminal while pin Q is output terminal. Path delay sets from input 50% transition to output high 90% transition or from input 50% transition to output low 10% transition to make sure output pin has already achieved goal electric potential. Fig. 3 illustrates that setup time means the time required for data to remain stable until the clock arrives, and hold time means the time required for data to remain stable after the clock arrives. Setup time was the time of signal from pin D to node 'm', and hold time were the time of signal from node 'm' to node 's' and the time of signal from pin D to node 'nm', and the bigger one was selected as the true hold time [3].

Linear Regression

In the practical application, circuits can run stably, the corresponding simulation result has no outlier. There are small differences in the parameters of each group, but the difference between groups was large, namely, there is no multicollinearity between features. Taking the above factors and more than one feature into account, we choose multiple linear regression to solve the regression problem.

$$h(x) = \sum_{i=0}^n \theta_i x_i = \theta^T X \quad (1)$$

Eq. 1 fits a linear model with coefficients $\theta = (\theta_1, \theta_2, \dots, \theta_n)$ and features X to minimize the residual sum of squares between the observed responses in the dataset, and the response predicted by the linear approximation. The value of coefficients θ will not be known, and it must be estimated from sample data. Classical least squares regression consists of minimizing the sum of the squared residuals [4, 5].

$$J(\theta) = \frac{1}{2} \sum_{i=1}^m (h_{\theta}(x^{(i)}) - y^{(i)})^2 \quad (2)$$

In Eq. 2, h_{θ} means the value predicted by linear model, and y means the real value of target, there are many methods to obtain the minimum value of $J(\theta)$: least squares and gradient descent. Batch gradient descent need to iterate through all the data at every iteration, so batch gradient descent only suits for small data. Stochastic gradient descent doesn't need traverse all of the data, it can only get close to the minimum value rather than the true minimum value. Least square is a very intuitive algorithm which calculates the minimum value by matrix operations. Cost function gets the minimum value when $\theta = (X^T X)^{-1} X^T Y$.

Method of Circuit Parameters

In this article, our purpose is to explain some detail of the extracting technique, the main features of the relationships hidden or implied in the tabulated figures. Nevertheless, the study of regression analysis techniques will also provide certain insights into how to plan the collection of data [6, 7].

As the smallest part of integrated circuits, metal-oxide-semiconductor field effect transistor (MOSFET) makes a difference to characterization of the circuits. The

MOSFET is a four-terminal device, and the four terminals are called drain (D), gate (G), source (S), and body (B) [8]. Each terminal affects the function of MOS, MOSFET and it's logical structure affects the function of circuits. So we select some parameters of MOS transistor and circuits as machine learning's features, and path delay as machine learning's target. According to [8], [9], [10], [11], we set some parameters of MOS in Table 2:

Table 2. Some parameters of MOS transistor.

I_{vin} [A]	The peak current of drive voltage when the signal flipping
I_{vdd} [A]	The peak current of pin VDD when the signal flipping
I_{vss} [A]	The peak current of pin VSS when the signal flipping
I_{on} [A]	The average current of MOS transistors after the signal flipped
I_{peak} [A]	The peak current of MOS transistors when the signal flipping
V_{th} [V]	The threshold voltage of MOS transistors when the signal flipping

Table 3. 5 Sets of INV's features and target.

I_{vin1} [10^{-6} A]	I_{vdd} [10^{-6} A]	I_{vss} [10^{-6} A]	V_{th1} [V]	V_{th2} [V]	I_{on1} [10^{-9} A]	I_{on2} [10^{-9} A]	I_{peak1} [10^{-5} A]	I_{peak2} [10^{-6} A]	Delay [10^{-11} s]
5.868	1.345	4.226	0.5129	0.5063	4.357	0.9851	1.650	4.074	3.146
4.419	1.020	3.226	0.2629	0.3713	1.663	2.142	1.064	3.672	2.527
7.076	9.112	11.97	0.2456	0.3713	5.097	4.475	2.466	13.06	1.859
6.802	1.614	5.830	0.4511	0.5922	2.508	0.6069	1.996	6.239	1.456
5.461	1.422	3.938	0.5768	0.4257	15.85	4.057	1.358	3.789	4.058

Table 4. Determination coefficients of 10 standard circuits.

R^2	INV	AND2	AND3	NOR2B	NOR2	AOI211	XOR3	ADDF	DFFNQ	DFFNSRPQ
train	0.968	0.973	0.968	0.982	0.989	0.960	0.989	0.995	0.996	0.971
test	0.962	0.930	0.952	0.973	0.983	0.924	0.962	0.962	0.965	0.940

Table 5. Relative error of 10 standard circuits.

δ	INV	AND2	AND3	NOR2B	NOR2	AOI211	XOR3	ADDF	DFFNQ	DFFNSRPQ
train	0.836	0.941	0.968	0.985	0.935	0.887	0.940	0.991	0.993	0.982
test	0.859	0.796	0.952	0.958	0.771	0.779	0.754	0.954	0.955	0.958

Take INV as an example, there are 325 sets of simulation data, 9 features and 1 target in each set. There are 5 sets of INV's features and targets in Table 3. The regression model uses 10-fold cross validation to obtain more accurate results [12]. As shown in Table 4 and Table 5, there were determination coefficients and relative error of training set and testing set in each circuits' regression [13]. By the definition of parameter, R^2 is very close to 1, which means that the regression fitting degree is very good, δ is also very close to 1, which means that the predicted timing is very accuracy.

Some circuits have many parameters of circuits, especially some parameters related to MOS transistors, such as I_{on} , I_{peak} , V_{th} , all MOS transistors have these parameters. There will be quite a few of circuit's parameters which make regression more complex.

Method of Path Delay

There is a method without MOS transistors' parameters to predict timing. Take DFFs as an example, the method collected path delay of non-DFFs as features and timing of DFFs as target. Non-DFFs include INV, AND2, AND3, NOR2B, NOR2, AOI211, XOR3 and ADDF. All of their path delay are features of machine learning, and timing of DFFs are target of machine learning. There are 5 sets of target in Table 6.

The regression model also uses 10-fold cross validation to obtain more accurate results. Table 7 lists determination coefficients of DFFs training set and testing set, Table 8 lists relative error of DFFs training set and testing set. By the definition of parameter, R^2 is especially close to 1, which means that the regression fitting degree is quite good, δ is also especially close to 1, which means that the predicted timing is quite accuracy. Comparing with the previous method, this method uses less feature, and the fitting effect is very good.

Table 6. Timing of DFFs in 5 process corners.

Process corner	DFFNQ			DFFNSRPQ		
	Path delay [10 ⁻¹¹ s]	Setup time [10 ⁻¹¹ s]	Hold time [10 ⁻¹¹ s]	Path delay [10 ⁻¹¹ s]	Setup time [10 ⁻¹¹ s]	Hold time [10 ⁻¹¹ s]
tt1p05v0c	7.766	8.880	5.857	9.717	11.92	8.879
ff1p26v125c	4.378	4.760	3.634	5.059	6.276	5.396
ss0p84vn40c	72.50	65.69	49.26	95.01	92.43	72.91
sf1p05v25c	7.999	9.969	5.928	9.793	12.46	8.312
fs1p05v85c	7.915	7.918	6.556	10.05	12.24	10.67

Table 7. Determination coefficients of DFFs.

R^2	DFFNQ			DFFNSRPQ		
	Path delay	Setup time	Hold time	Path delay	Setup time	Hold time
Training set	0.9991	0.9996	0.9989	0.9990	0.9996	0.9990
Testing set	0.9984	0.9987	0.9980	0.9979	0.9992	0.9983

Table 8. Relative error of DFFs.

δ	DFFNQ			DFFNSRPQ		
	Path delay	Setup time	Hold time	Path delay	Setup time	Hold time
Training set	0.9923	0.9907	0.9772	0.9981	0.9946	0.9763
Testing set	0.9912	0.9821	0.9874	0.9901	0.9846	0.9854

Conclusions

Based on the standard cell library as an example, this article attempted to propose two methods to predict timing. The previous method used parameters of circuits as features and timing as target, and the last method used timing of circuits as features and timing of DFFs as target. The results showed both of them can achieved good results. Method of timing fitted better and predicted target more accurately. From this point of view, it is feasible to predict timing by linear regression, which also provides a feasible idea to predict timing of SRAM compiler.

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